



# SLOVENSKI STANDARD

## SIST EN 61760-3:2010

01-september-2010

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### Tehnologija površinske montaže - 3. del: Standardne metode za specifikacijo komponent za spajkanje "Through Hole Reflow" (THR) (IEC 61760-3:2010)

Surface mounting technology - Part 3: Standard method for the specification of components for Through Hole Reflow (THR) soldering (IEC 61760-3:2010)

Oberflächenmontagetechnik - Teil 3: Genormtes Verfahren zur Spezifizierung von Durchsteckmontage-Bauelementen für das Aufschmelzlöten (THR) (IEC 61760-3:2010)

Technique du montage en surface - Partie 3: Méthode normalisée relative à la spécification des composants pour le brasage par refusion à trous traversants (THR, Through Hole Reflow) (CEI 61760-3:2010)

**Ta slovenski standard je istoveten z: EN 61760-3:2010**

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#### **ICS:**

31.020	Elektronske komponente na splošno	Electronic components in general
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**SIST EN 61760-3:2010**

**en**

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EUROPEAN STANDARD  
NORME EUROPÉENNE  
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**EN 61760-3**

April 2010

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English version

**Surface mounting technology -  
Part 3: Standard method for the specification of components  
for Through Hole Reflow (THR) soldering  
(IEC 61760-3:2010)**

Technique du montage en surface -  
Partie 3: Méthode normalisée relative  
à la spécification des composants pour  
le brasage par refusion à trous traversants  
(THR, Through Hole Reflow)  
(CEI 61760-3:2010)

Oberflächenmontagetechnik -  
Teil 3: Genormtes Verfahren  
zur Spezifizierung  
von Durchsteckmontage-Bauelementen  
für das Aufschmelzlöten (THR)  
(IEC 61760-3:2010)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Management Centre: Avenue Marnix 17, B - 1000 Brussels**

## Foreword

The text of document 91/856/CDV, future edition 1 of IEC 61760-3, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61760-3 on 2010-04-01.

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The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2011-01-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2013-04-01

Annex ZA has been added by CENELEC.

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## Endorsement notice

The text of the International Standard IEC 61760-3:2010 was approved by CENELEC as a European Standard without any modification.

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60062	-	Marking codes for resistors and capacitors	EN 60062	-
IEC 60068	Series	Environmental testing	EN 60068	Series
IEC 60068-2-20	-	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	-
IEC 60068-2-21	-	Environmental testing - Part 2-21: Tests - Test U: Robustness of terminations and integral mounting devices	EN 60068-2-21	-
IEC 60068-2-45 + A1	1980 1993	Environmental testing - Part 2: Tests - Test Xa and guidance: Immersion in cleaning solvents	EN 60068-2-45 + A1	1992 1993
IEC 60068-2-58	-	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	-
IEC 60068-2-77	-	Environmental testing - Part 2-77: Tests - Test 77: Body strength and impact shock	EN 60068-2-77	-
IEC 60068-2-82	-	Environmental testing - Part 2-82: Tests - Test XW1: Whisker test methods for electronic and electric components	EN 60068-2-82	-
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IEC 60286	Series	Packaging of components for automatic handling	EN 60286	Series
IEC 60286-3	-	Packaging of components for automatic handling - Part 3: Packaging of surface mount components on continuous tapes	EN 60286-3	-
IEC 60286-4	-	Packaging of components for automatic handling - Part 4: Stick magazines for electronic components encapsulated in packages of form E and G	EN 60286-4	-

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60286-5	-	Packaging of components for automatic handling - Part 5: Matrix trays	EN 60286-5	-
IEC 60749-20	-	Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat	EN 60749-20	-
IEC 61760-2	-	Surface mounting technology - Part 2: Transportation and storage conditions of surface mounting devices (SMD) - Application guide	EN 61760-2	-
IEC 62090	-	Product package labels for electronic components using bar code and two-dimensional symbologies	EN 62090	-
ISO 8601	-	Data elements and interchange formats - Information interchange - Representation of dates and times	-	-

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# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Surface mounting technology –**  
**Part 3: Standard method for the specification of components for through hole reflow (THR) soldering**

**Technique du montage en surface –**  
**Partie 3: Méthode normalisée relative à la spécification des composants pour le brasage par refusion à trous traversants (THR, Through Hole Reflow)**

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## SURFACE MOUNTING TECHNOLOGY –

## Part 3: Standard method for the specification of components for through hole reflow (THR) soldering

## FOREWORD

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International Standard IEC 61760-3 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

CDV	Report on voting
91/856/CDV	91/898/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61760 series, under the general title *Surface mounting technology* can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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